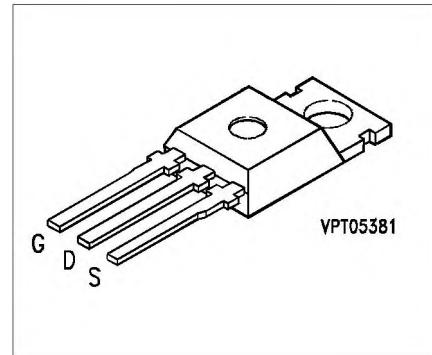


SIPMOS® Power Transistor**BUZ 22**

- N channel
- Enhancement mode
- Avalanche-rated



Type	V_{DS}	I_D	$R_{DS\ (on)}$	Package ¹⁾	Ordering Code
BUZ 22	100 V	34 A	0.055 Ω	TO-220 AB	C67078-S1333-A2

Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current, $T_C = 27^\circ\text{C}$	I_D	34	A
Pulsed drain current, $T_C = 25^\circ\text{C}$	$I_{D\ puls}$	136	
Avalanche current, limited by $T_{j\max}$	I_{AR}	34	
Avalanche energy, periodic limited by $T_{j\max}$	E_{AR}	15	mJ
Avalanche energy, single pulse $I_D = 34\text{ A}$, $V_{DD} = 25\text{ V}$, $R_{GS} = 25\text{ }\Omega$ $L = 285.5\text{ }\mu\text{H}$, $T_j = 25^\circ\text{C}$	E_{AS}	220	
Gate-source voltage	V_{GS}	± 20	V
Power dissipation, $T_C = 25^\circ\text{C}$	P_{tot}	125	W
Operating and storage temperature range	T_j , T_{stg}	- 55 ... + 150	°C

Thermal resistance, chip-case	$R_{th\ JC}$	≤ 1.0	K/W
DIN humidity category, DIN 40 040		E	-
IEC climatic category, DIN IEC 68-1		55/150/56	

1) See chapter Package Outlines.

Electrical Characteristicsat $T_j = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Static characteristics

Drain-source breakdown voltage $V_{GS} = 0 \text{ V}, I_D = 0.25 \text{ mA}$	$V_{(BR) DSS}$	100	-	-	V
Gate threshold voltage $V_{GS} = V_{DS}, I_D = 1 \text{ mA}$	$V_{GS (\text{th})}$	2.1	3.0	4.0	
Zero gate voltage drain current $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	I_{DSS}	-	0.1	1.0	μA
-	-	10	100	100	
Gate-source leakage current $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$	I_{GSS}	-	10	100	nA
Drain-source on-resistance $V_{GS} = 10 \text{ V}, I_D = 22 \text{ A}$	$R_{DS (\text{on})}$	-	0.05	0.055	Ω

Dynamic characteristics

Forward transconductance $V_{DS} \geq 2 \times I_D \times R_{DS(\text{on})\text{max}}, I_D = 22 \text{ A}$	g_{fs}	10	17.5	-	S
Input capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{iss}	-	1400	1850	pF
Output capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{oss}	-	450	700	
Reverse transfer capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{rss}	-	230	370	
Turn-on time t_{on} , ($t_{on} = t_{d(on)} + t_r$) $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}, R_{GS} = 50 \Omega$	$t_{d(on)}$	-	20	30	ns
-	t_r	-	80	120	
Turn-off time t_{off} , ($t_{off} = t_{d(off)} + t_f$) $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}, R_{GS} = 50 \Omega$	$t_{d(off)}$	-	230	300	
-	t_f	-	120	160	

Electrical Characteristics (cont'd)
at $T_j = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

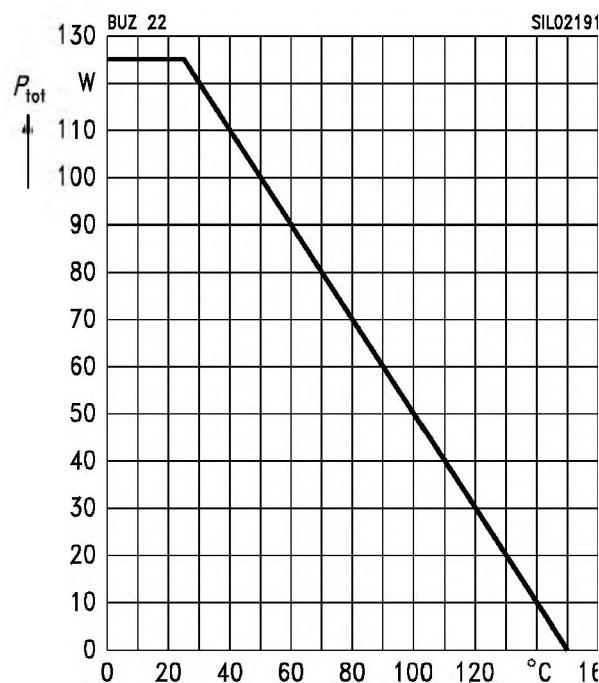
Reverse diode

Continuous reverse drain current $T_C = 25^\circ\text{C}$	I_S	–	–	34	A
Pulsed reverse drain current $T_C = 25^\circ\text{C}$	I_{SM}	–	–	136	
Diode forward on-voltage $I_S = 68 \text{ A}, V_{GS} = 0 \text{ V}$	V_{SD}	–	1.4	1.8	V
Reverse recovery time $V_R = 30 \text{ V}, I_F = I_S, di_F / dt = 100 \text{ A}/\mu\text{s}$	t_{rr}	–	130	–	ns
Reverse recovery charge $V_R = 30 \text{ V}, I_F = I_S, di_F / dt = 100 \text{ A}/\mu\text{s}$	Q_{rr}	–	0.7	–	μC

Characteristics at $T_i = 25^\circ\text{C}$, unless otherwise specified.

Total power dissipation

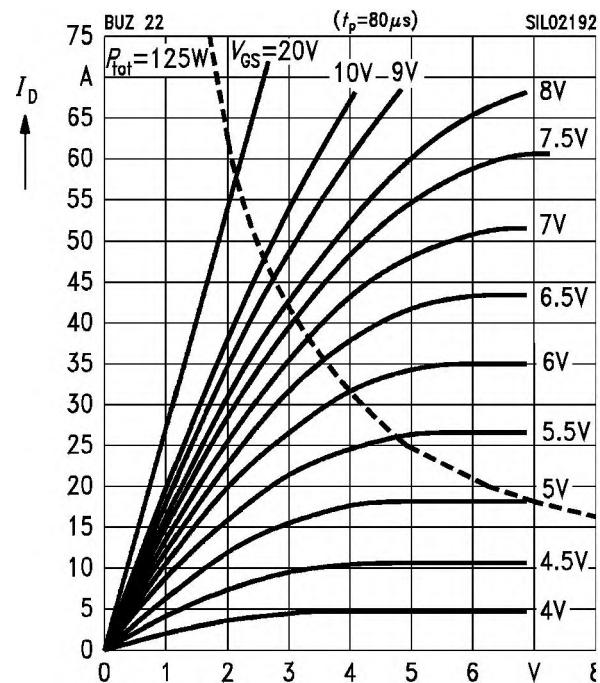
$$P_{\text{tot}} = f(T_C)$$



Typ. output characteristics

$$I_D = f(V_{DS})$$

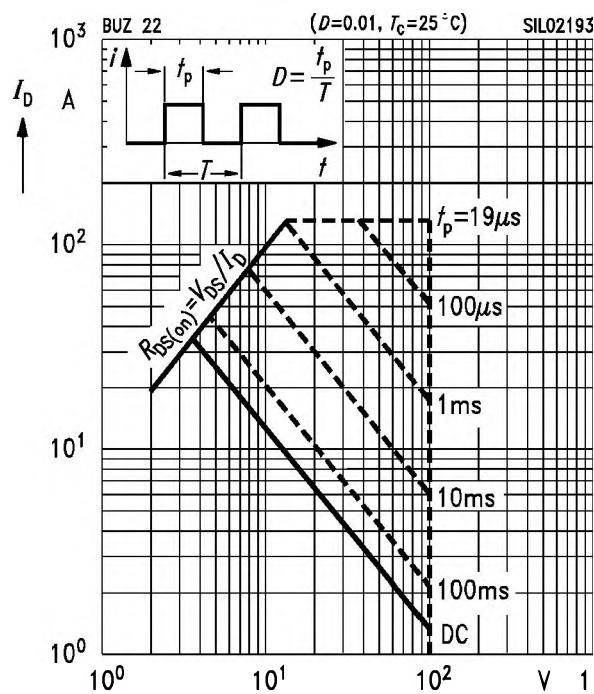
parameter: $t_p = 80 \mu\text{s}$



Safe operating area

$$I_D = f(V_{DS})$$

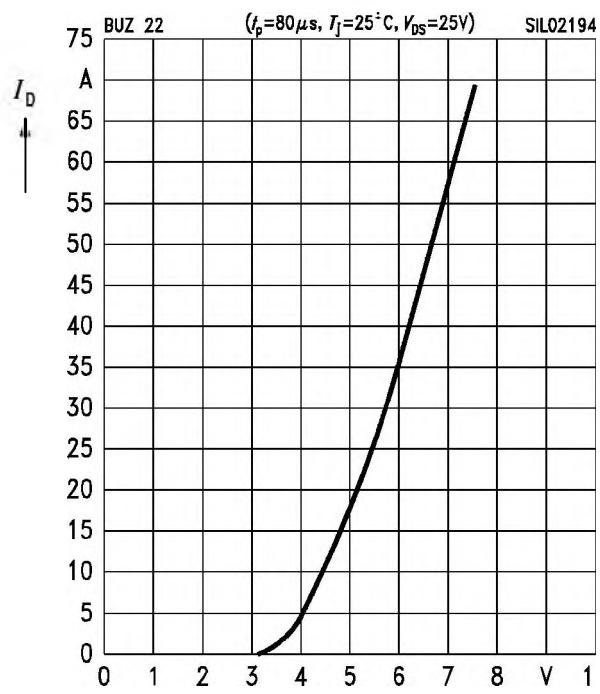
parameter: $D = 0.01$, $T_C = 25^\circ\text{C}$



Typ. transfer characteristics

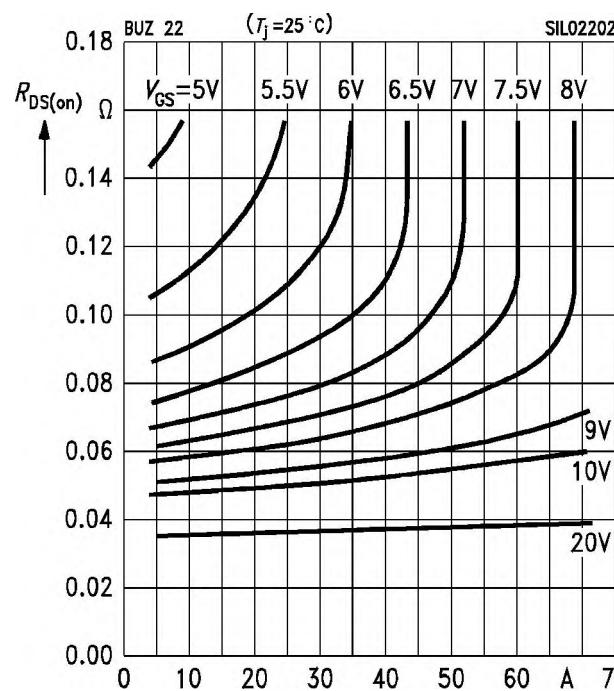
$$I_D = f(V_{GS})$$

parameter: $t_p = 80 \mu\text{s}$, $V_{DS} = 25 \text{ V}$

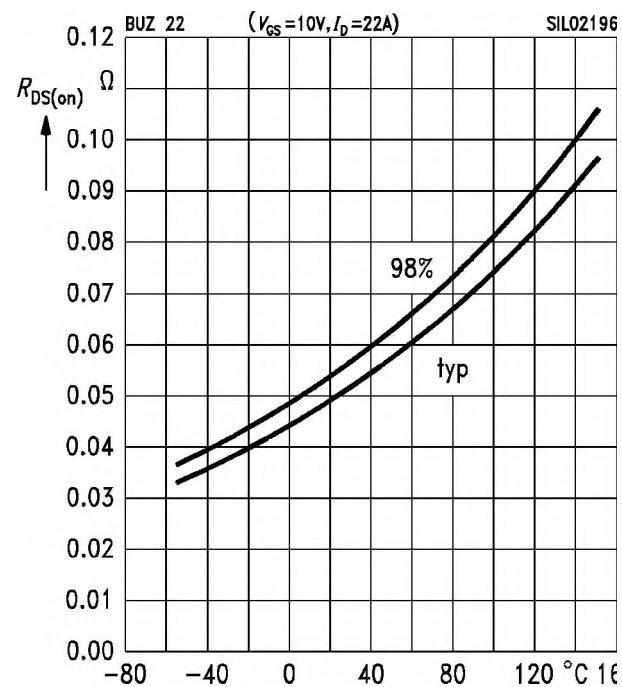


Typ. drain-source on-resistance

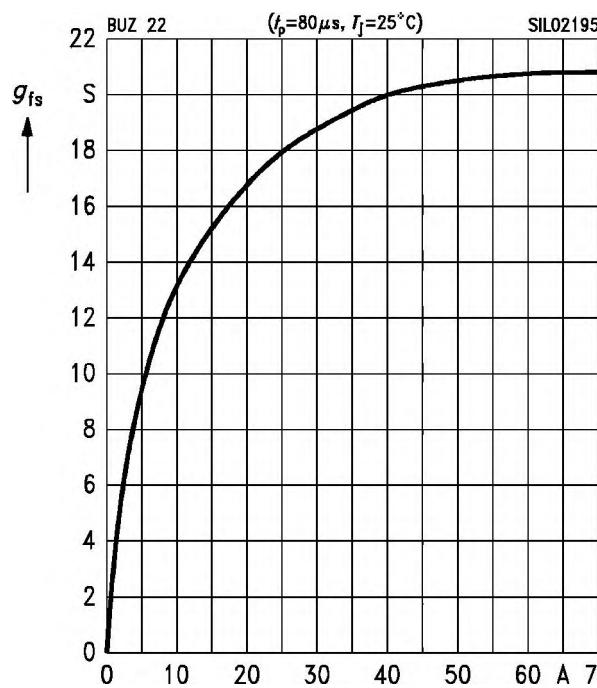
$$R_{DS(on)} = f(I_D)$$

parameter: V_{GS} **Drain-source on-resistance**

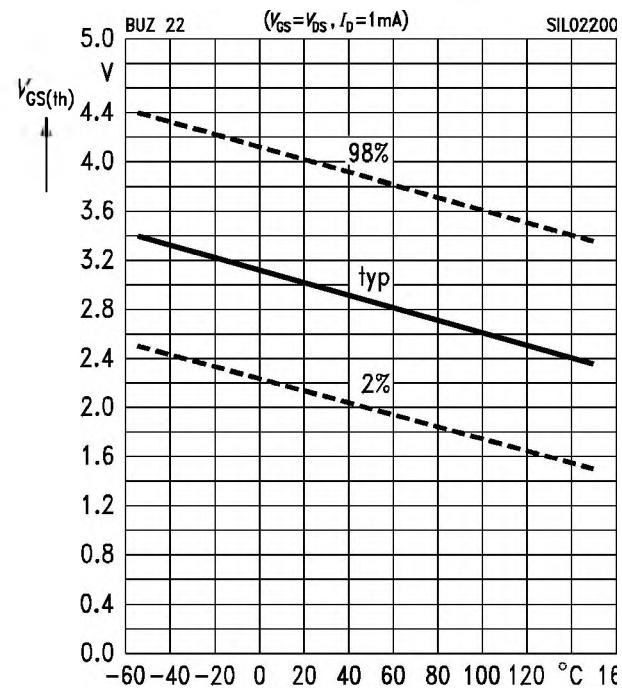
$$R_{DS(on)} = f(T_j)$$

parameter: $I_D = 22 \text{ A}$, $V_{GS} = 10 \text{ V}$, (spread)**Typ. forward transconductance**

$$g_{fs} = f(I_D)$$

parameter: $t_p = 80 \mu\text{s}$ **Gate threshold voltage**

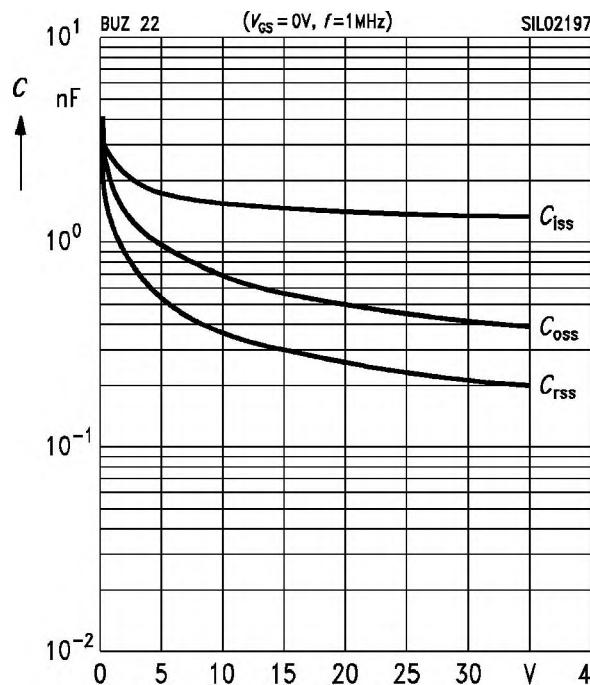
$$V_{GS(th)} = f(T_j)$$

parameter: $V_{GS} = V_{DS}$, $I_D = 1 \text{ mA}$, (spread)

Typ. capacitances

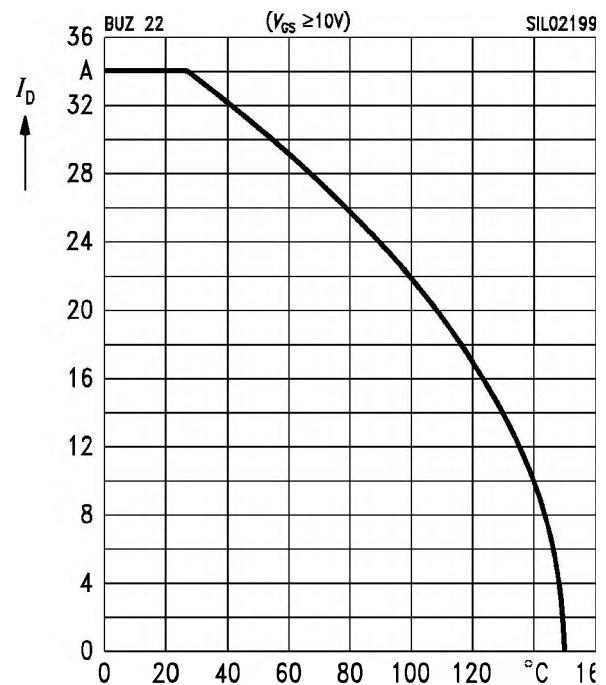
$$C = f(V_{DS})$$

parameter: $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$

**Drain current**

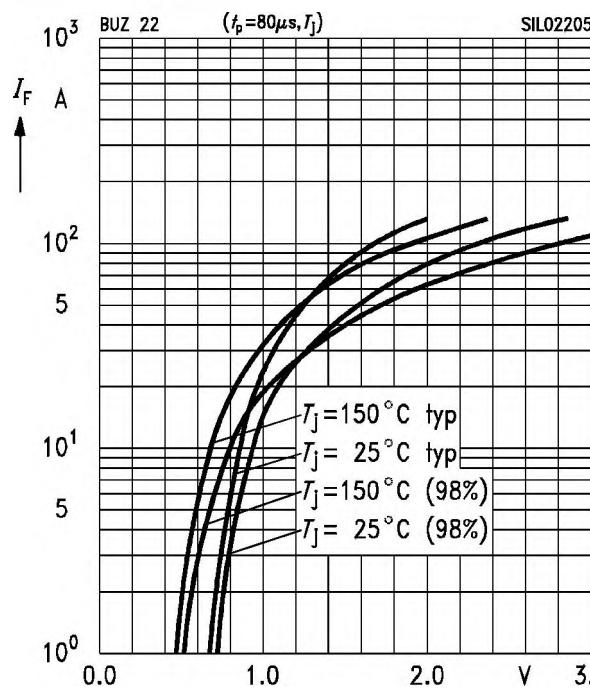
$$I_D = f(T_C)$$

parameter: $V_{GS} \geq 10 \text{ V}$

**Forward characteristics of reverse diode**

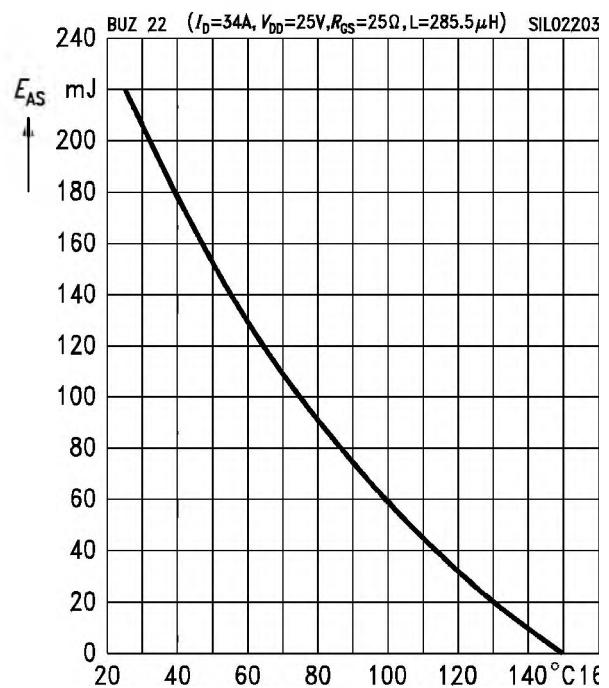
$$I_F = f(V_{SD})$$

parameter: T_j , $t_p = 80 \mu\text{s}$, (spread)

**Avalanche energy $E_{AS} = f(T_j)$**

parameter: $I_D = 34 \text{ A}$, $V_{DD} = 25 \text{ V}$

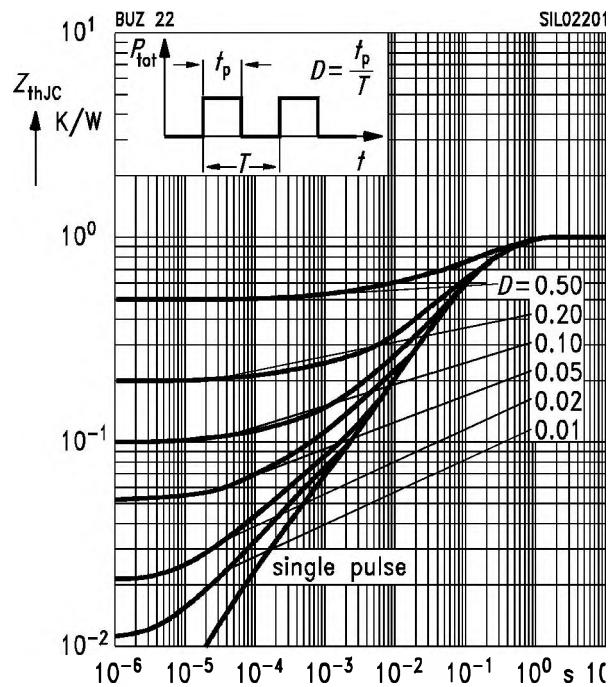
$R_{GS} = 25 \Omega$, $L = 285.5 \mu\text{H}$



Transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

parameter: $D = t_p / T$

**Typ. gate charge**

$$V_{\text{GS}} = f(Q_{\text{Gate}})$$

parameter: $I_{D \text{ puls}} = 51.0 \text{ A}$

